

SPECIFICATION AND PERFORMANCE

Series	115U-B210	File	115U-B210	Date	2025/03/06
--------	-----------	------	-----------	------	------------

Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of below:

Connector:

P/N	Descriptions
115U-B210	Micro SD and Nano SIM Socket, Stack Type, Tray Push-Pull, w/Lock and Switch, 10u", C7025, Reel

Card tray:

P/N	Descriptions
115U-T009	Card Tray, Micro SD & Nano SIM, PBT, Black, Bag, 19.6mm
115U-T010	Card Tray, Micro SD & Micro SIM, PBT, Black, Bag, 19.6mm
115U-T012	Card Tray, Micro SD & Nano SIM, PBT, Black, Bag 21.6mm
115U-T013	Card Tray, Micro SD & Micro SIM, PBT, Black, Bag, 21.6mm
115U-T019	Card Tray for 115U-B210, Waterproof, Nano SIM & Micro SD, PBT, black, Bag, L=23.6
115U-T020	Card Tray for 115U-B210, Waterproof, Micro SIM & Micro SD, PBT black, Bag, L=23.6

Performance and Descriptions:

The product is designed to meet the specifications for electrical, mechanical, and environmental performance requirements. Unless otherwise specified, all tests are conducted under ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIALS

NO.	PART NAME	DESCRIPTION
1	HOUSING	LCP E130i, UL94-V0, black or equivalent
2	CONTACT	Cu-Ni-Si Copper alloy C7025 0.12t, 10u" Min. gold plating on contact area, 120u" Min. matte-tin plating on solder area, under plating 50u" Min. nickel over all
3	SLIDER	LCP E130i, UL94-V0, black or equivalent
4	SHELL	Stainless steel SUS304, 0.15t, 50u" Min. nickel plating over all

CARD TRAY:

1	BODY	PBT 4130, UL94V-0, black or equivalent
---	------	--



RATING

Rated Voltage	10V
Rated Current	0.5A
Operating Temperature	-40°C to +105°C
Storage Temperature	-40°C to +85°C
Durability	100 cycles

ELECTRICAL

Item	Requirement	Test Condition
Low Level Contact Resistance	100mΩ Max.	Solder connectors to PCB and insert dummy card, measure by applying closed circuit current of 10mA maximum at open circuit voltage of 20mV (max). (Per EIA-364-23)
Dielectric Withstanding Voltage	No Broken	500V AC (rms.) between two adjacent for 1 minute. (Trip current:1mA) (Per EIA-364-20)
Insulation Resistance	1000MΩ Min.	Apply 500V DC between adjacent contacts, or contact and ground. (EIA-364-21)
Temperature Rise	30°C max.	EIA-364-70 Mate connectors, measure the temperature rise at rated current after 0.5A/Power contact. The temperature rise above ambient shall not exceed 30°C the ambient condition is still air at 25°C.

MECHANICAL

Item	Requirement	Test Condition
Contact Normal Force	0.5N Max. per Pin	Take contact insert molding semi-finished products, no other parts, fixed in jig, measure contact normal force at the speed rate of 25 mm/min.
Durability	100 cycles, LLCR 100 mΩ Max.	Use manual operation, Solder connectors to PCB, 400 to 600 cycles per hours (EIA364-09)

ENVIRONMENTAL

Item	Requirement	Test Condition
Vibration	Discontinuity < 1 ms	EN60721-3-5 Class 5M3 Random vibration Test (3.38Grms) 10~500Hz, 3.38Grms, 1hr/per axis Test PSD: 10~200Hz: 3m ² /S ³ , 200~500Hz, 1m ² /S ³
Mechanical Shock	Discontinuity < 1 ms	EN60721-3-5 Class 5M3 Shock Test-Level II (100G/6ms)



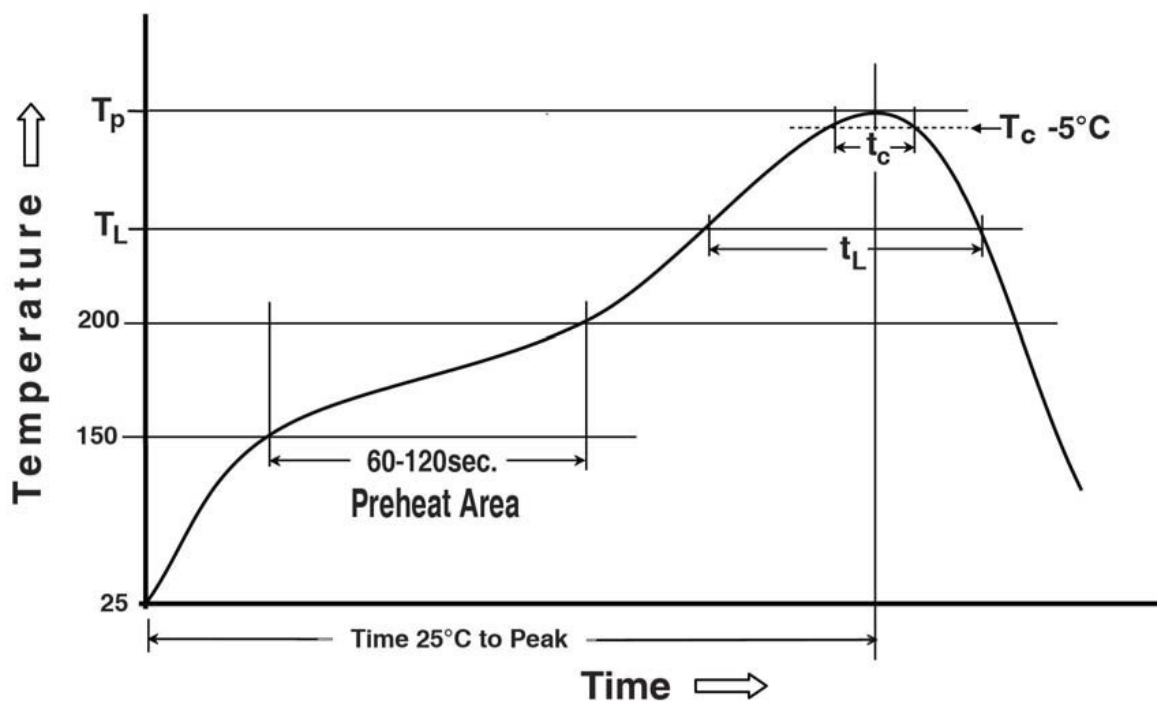
Temperature Life	Contact resistance 100 mΩ Max.	105±2°C Mated, series between samples, loading 5V DC/60 mA, duration 96 hours (EIA-364-17, method B, condition 4)
Thermal Shock	Max. Change from initial contact Resistance 40mΩ Max No physical damage to connector shall occur.	Temperature Range: -55 to 85°C No. of Cycles: 5 cycles for 1 hours (EIA364-32)
Cold Resistance	Contact resistance 100 mΩ Max.	-40°C/96Hr (EIA-364-59)
Humidity	Meets ELECTRICAL requirements	Temperature : 70±2°C Relative humidity : 90~95% Duration : 96 hours
Salt Water Spray	No oxidation Contact resistance 100 mΩ Max.	Temperature : 35±2°C Salt water density : 5±1% Duration : 48 hours

SOLDER ABILITY

Item	Requirement	Test Condition
Solder ability	95% of immersed area must show no voids, pin holes	The termination should be 95% covered with new continuous solder coating Solder temperature: 245±5°C Test time: 3±0.5 seconds, (Per EIA-364-71)
Resistance to soldering heat	No melting, cracks or functional damage allowed	Preheating temperature: 150 ~ 200°C, 60~120 seconds Liquidus temperature (TL): 217°C, 60~150 seconds Peak temperature: 260°C Time within 5 °C of peak temperature (Tc): 255°C, 30seconds



Reflow Profile



Preheating temperature: 150 ~ 200°C, 60~120 seconds

Liquidus temperature (TL): 217°C, 60~150 seconds

Peak temperature: 260°C

Time within 5 °C of peak temperature (Tc): 255°C, 30seconds